



Product Change Notification

113379 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 113379 - 00
Change Title: Intel® Server System R2208LT2HKC4
PCN 113379-00, Product Design
Update Raid Module
Date of Publication: November 5, 2014

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	November 20, 2014
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

Description of Change to the Customer:

Intel will implement the following changes on the Intel® Server System R2208LT2HKC4:

1. The Intel® Integrated RAID Module RMS25PB080 is being updated with D1 Stepping chipset from C1 Stepping. This change allows for PCI Express* 3.0 functionality.
2. The raid module firmware has been updated to version v23.28.0 0010, which support the D1 stepping chipset, and can set the RAID module cache policy from Write Back to Write Through when a scheduled learn cycle of the RAID Maintenance Free Backup Unit fails to complete successfully.
3. Certain capacitor values of the Intel® Integrated RAID Module RMS25PB080 are increased to defensively improve stability. Change C3L55 from 10uF 0603 to 22uF 0603; change C4L92 from 0.01uF to 2.2uF.
4. Disable the PCIe* 3.0 link speed setting in the Serial Bootstrap Room (SBR) on the RAID module. This change can force the RAID module to run at PCIe* 2.0 link speed to achieve a stable PCIe* communication with the server system. The SBR setting only can be changed at Intel manufactory.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes. Customers may need to validate the function and feature changes once the post-change system is available.

Products Affected / Intel Ordering Codes:

CORE SKU			
Product Code	MM#	Pre Change TA	Post Change TA
R2208LT2HKC4	919479	G45890-008	G45890-009

PCN Revision History:**Date of Revision:**

November 5, 2014

Revision Number:

00

Reason:

Originally Published PCN